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J1000 U.S. PTO
09/852824



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: P002-2

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

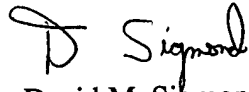
Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98,
Applicant hereby submits the enclosed Form PTO-1449.

Copies of documents cited on the enclosed Form PTO-1449 are not enclosed because
they were previously cited by or submitted to the U.S. Patent Office in prior U.S. Application
Serial No. 09/465,024 filed December 16, 1999. The above-identified application is a divisional
of the prior application.

The filing of this Information Disclosure Statement shall not be construed as a
representation that a search has been made, an admission that any of these documents, alone or in
any combination, is considered to be material to patentability, an admission that any of these
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any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office
Action. Accordingly, no fee is due.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "D Sigmond". The signature is written in a cursive, flowing style.

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